

## TECH DATA SHEET

# ILR-1401 – HIGH TEMPERATURE STABLE RESIN (FM51-24)



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## DESCRIPTION

ILR-1401 is a high molecular weight, curable oligomer mixture suitable for use as the base resin in a variety of microelectronic assembly applications. The resin is supplied pre-dissolved in anisole (methoxy benzene) for ease of incorporation. The unique ILR-1401 joins the nature of a thermoplastic resin (flexibility, high strength) and a thermoset resin (curability, hydrophobicity, ease of customer use) together with superior electrical properties for the next generation of high frequency applications.

## HIGHLIGHTS

- Very low material shrinkages
- Flexible / high strength
- Curability
- Very low modulus
- Hydrophobic / low water absorption
- Ease of customer use

## TYPICAL PHYSICAL AND CHEMICAL PROPERTIES

PROPERTY	METHOD	RESULT
TGA, °C	Td(5%)	453
CTE ( $\alpha_1$ ), ppm/°C	TMA	80
Tg, °C	TMA	145.5
	DMA	183.7
Modulus @25C, MPa	DMA	460
Dk	AET, 20GHz	2.4
Df	AET, 20GHz	0.0018

*Data is for reference only and we recommend use of this data as a guide..*

## RECOMMENDED APPLICATION:

R1401 is suggested for use in applications that require high temperature resin performance such as CCL.

## INSTRUCTIONS FOR USE:

**APPLICATION - ILR-1401** MAY BE APPLIED BY NORMAL MEANS – SPIN COATING, DISPENSE TECHNIQUES OR EVEN JETTING.

**DRYING - ILR-1401** DRYING CONDITION : 30~60MIN @100°C

**CURING - ILR-1401** CURE CONDITION : 1HR~2HRS @200°C HOMOPOLYMERIZATION

## CONTACT:

### REQUEST A SAMPLE OR PLACE AN ORDER

Customer Support

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REF: DMI Part Number: R1401